

Docket No.: 4590-397

PATENT**Amendments to the Specification:**

Please replace the first full paragraph on page 2, line 7 through 17 with the following amended paragraph:

In practice, for relatively complex functions, it is necessary to use a large number of MMIC integrated circuit chips, since the quantity of circuit elements that can be placed in one and the same chip is far more limited for the MMIC circuits than for the low frequency circuits made of silicon. Also, these chips are mounted on a substrate with interconnections that are difficult to produce given the very high working frequencies. The design of the interconnections is difficult, and the production cost is high because of the precision required in maintaining ~~light~~ tight tolerances to ensure the transmission of the millimetric frequency signals. This becomes all the more true as the number of MMIC chips increases in the system. Also, the increase in complexity of the functions that are to be produced brings with it an increase in the number of chips.

Please replace the third full paragraph on page 3, line 13 through 17 with the following amended paragraph:

The package is preferably provided with a conductive cover positioned at a distance from the first port such that create, near this port, an electromagnetic short circuit at the main working frequency, this short circuit forming a wave reflector facilitating the contactless transmission of this frequency through the first port.

Please replace the second full paragraph on page 6, line 6 through 21 with the following amended paragraph:

The package is conductive, for example metallic or partially metallic; it preferably includes a metallic base 20, serving as a substrate on which is directly mounted the rear face of the MMIC chip 22, a double-sided ceramic substrate 24 providing the interconnections inside the package and towards the outside of the package, and a metallic or metallized cover 25 covering the base,

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to enclose, between the base and the cover, the chip or chips and the ceramic substrate. Since the MMIC chip 22 is welded directly onto the base, the ceramic substrate 24 includes an opening in which the chip is inserted. The ceramic substrate 24 is preferably a substrate metallized on both sides: as shown in Figures 1 and 2, metallization 26 on the front side forms the transmission lines, and metallization 28 on the rear side [[to]] forms a ground plane. The dimensions of the various dielectric and conductive parts are such that the component operates correctly at the working frequency concerned (77 GHz). The metallizations 26 and 28 are used, to create the interconnections between chips and, [[,]] to create the external ports of the package, both the ports capable of working at 77 GHz and the ports designed to transmit a frequency that is a subharmonic at 77 GHz.